

AMENDMENTS TO THE CLAIMS

1-22. (Cancelled)

23. (Currently Amended) A method of forming a conductive pattern, comprising:
illuminating a photographic film with a desired illumination configuration;
developing the photographic film so that illuminated or non-illuminated portions of the film are adjusted to be in an altered state; and
selectively depositing additional conductive material onto portions of the film in an altered state in amounts greater than amounts of conductive material deposited on portions of the film not in the altered state,
wherein the additional conductive material is deposited via electroless deposition.

24. (Cancelled)

25. (Original) The method of claim 24 further comprising electroplating additional metal on the metal deposited via the electroless deposition.

26. (Original) The method of claim 23 wherein the conductive pattern is a circuit.

27. (Currently amended) A method of forming a discontinuous metallic structure comprising:
illuminating a photographic film with a desired structure configuration;
developing the photographic film so that illuminated or non-illuminated portions of the film are adjusted to be in an altered state; and
selectively depositing additional conductive material onto portions of the film in an altered state in amounts greater than amounts of conductive material deposited on portions of the film not in the altered state,
wherein the additional conductive material is deposited via electroless deposition.

28. (Cancelled)

29. (Original) The method of claim 28 wherein the additional conductive material is nickel.